KetaSpire® KT-820SFP
polyetheretherketone

KetaSpire® KT-820SFP is the low flow grade of unreinforced polyetheretherketone (PEEK) supplied in a natural-colored, super-fine powder form. This super-fine PEEK powder is suitable for water-borne coatings, electrostatically driven powder coatings, and resin pre-impregnation of continuous fiber composites. This super-fine powder is produced to a median particle size D50 of about 30 micrometers.

KetaSpire® PEEK is produced to the highest industry standards and is characterized by a distinct combination of properties, which include excellent chemical resistance to acids, bases and a broad range of aggressive organic chemicals, best in class fatigue resistance, high thermal resistance, high purity and ease of melt processing.

These properties make KT-820SFP well-suited for applications in health care, transportation, electronics, chemical processing and other industrial uses.

The resin is also available in a natural-colored pellet form under the grade name KT-820 NT for injection molding and extrusion

General		
Material Status	• Commercial: Active	
Availability	• Africa & Middle East • Asia Pacific • Europe	• Latin America • North America
Features	• Chemical Resistant • Ductile • Fatigue Resistant • Flame Retardant	• Good Dimensional Stability • Good Impact Resistance • High Heat Resistance
Uses	• Aerospace Applications • Automotive Applications • Electrical/Electronic Applications	• Industrial Applications • Oil/Gas Applications
RoHS Compliance	• Contact Manufacturer	
Appearance	• Natural Color	
Forms	• Powder	
Processing Method	• Electrostatic Spray Coating	• Water-borne Coating

Physical	Typical Value	Unit	Test method
Density / Specific Gravity	1.30		ASTM D792
Melt Mass-Flow Rate (MFR) (400°C/2.16 kg)	3.0	g/10 min	ASTM D1238
Water Absorption (24 hr)	0.10	%	ASTM D570
Particle Size			
D50	30.0	µm	
D90	60.0	µm	
D99	125	µm	

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Mechanical	Typical Value	Unit	Test method
Tensile Modulus	3650	MPa	ASTM D638
Tensile Strength	96.5	MPa	ASTM D638
Tensile Elongation			ASTM D638
Yield	5.2	%	
Break[1]	20 to 30	%	
Flexural Modulus	3860	MPa	ASTM D790
Flexural Strength	152	MPa	ASTM D790

Impact	Typical Value	Unit	Test method
Notched Izod Impact	69	J/m	ASTM D256
Unnotched Izod Impact	No Break		ASTM D4812

Thermal	Typical Value	Unit	Test method
Deflection Temperature Under Load			ASTM D648
1.8 MPa, Unannealed	157	°C	
Glass Transition Temperature	150	°C	ASTM D3417
Melting Temperature	340	°C	ASTM D3417
CLTE - Flow (-50 to 50°C)	4.3E-5	cm/cm/°C	ASTM E831

Fill Analysis	Typical Value	Unit	Test method
Melt Viscosity (400°C, 1000 sec^-1)	420	Pa·s	ASTM D3835

Injection Notes
Back Pressure: minimum

Notes

Typical properties: these are not to be construed as specifications.

[1] Tensile test speed = 2 in/min (50 mm/min)

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Safety Data Sheets (SDS) are available by emailing us or contacting your sales representative. Always consult the appropriate SDS before using any of our products.

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